

						Package Homogeneous Materials					
Device Type:		1N5811US		UFR,FRR B-Body Sq. Melf							
Basic Substance		CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	19.80	(mg) Total	Glass	% of Total Weight	10.95
Schott 8651 Glass		Trade Secret	Glass	10.95	19.80	109502		Schott 8651 Glass	Trade Secret	100.00	
Tungsten		7440-33-7	Plug	47.89	86.58	478912	Total 100.00				
Silicon		7440-21-3	Die	1.65	2.98	16462					
Silver		7440-22-4	End Cap Preform	1.40	2.52	13951	86.58	(mg) Total	Plug	% of Total Weight	47.89
Copper		7440-50-8	End Cap Preform	0.59	1.07	5939		Tungsten	7440-33-7	100.00	
Tin		7440-31-5	End Cap Preform	0.16	0.29	1614	Total 100.00				
OFHC COPPER		7440-50-8	End Cap	37.36	67.54	373619					
TOTALS:				100.00	180.78	1,000,000	2.98	(mg) Total	Die	% of Total Weight	1.65
180.78 mg Total Mass								Silicon	7440-21-3	100.00	
Total 100.00											
The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.											
Microchip Technology Incorporated designs all products to comply with global product material compliance standards, including but not limited to RoHS, REACH, and China RoHS. Additionally, Microchip products are designed to be compliant with IEC62474. For specific compliance information, please check our product material compliance website on microchip.com or ask your local sales representative.											
Microchip Technology Incorporated believes the information in this MCD is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts. These estimates do not include trace levels of dopants, impurities, metals, and non-metallic materials which may be contained within silicon devices (silicon IC) or the finished parts.											
Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the Information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated, and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgements, and invoices.											
Microchip disclaims any duty to notify users of updates or changes to MCDs and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in MCDs.											
3.89		(mg) Total	End Cap Preform	% of Total Weight	2.15						
		Silver	7440-22-4	64.88							
		Copper	7440-50-8	27.62							
		Tin	7440-31-5	7.50							
		Total	100.00								
67.54		(mg) Total	End Cap	% of Total Weight	37.36						
		OFHC COPPER	7440-50-8	100.00							
		Total	100.00								